



LMP SOLDER PASTE

DISPENSING GRADE

"sirius™ 1 LF"



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SIRIUS™ 1 LF no-clean and lead free solder paste is carefully formulated to confer high activity soldering and yet, leaves very low clear, benign residues.

- Halide-free.
- High activity.
- Low and safe residue.
- Fast print capabilities (up to 150mm/s).
- Long abandon time (>24 hours).
- Extended tack-life (>24 hours).
- Long stencil-life (>24 hours).
- Fine-pitch (400µm) and ultra-fine pitch (<300µm) capabilities.

SIRIUS™ 1 LF no-clean solder paste is made to strict quality assurance standards.

Alloy	Metal (%)	Viscosity (cP)
Sn43Bi57	86.0	300,000 – 500,000
Sn42Bi57Ag1	86.0	300,000 – 500,000
Sn42Bi57.6Ag0.4	86.0	300,000 – 500,000
Melting point	138°C	

Printing

Stencil

Stainless steel, brass or nickel. Chemical etched, laser cut or electroformed.

Squeegee

Stainless steel or 80-100 durometer polyurethane.

Print speed

50-150 mm/s. Best results: 80 to 120 mm/s
Generally slower for fine pitch.

Squeegee pressure

5-10 Kg. Generally higher for fine pitch.

Snap-off

0 to 0.25mm. On contact printing is preferred.

Ambient Conditions

18-22°C and 35% to 70% RH. Minimize exposure of paste direct to air flow.

Cleanup-Stencils and Tools

Most stencil wipes and stencil cleaners.

Reflow

Heating Methods

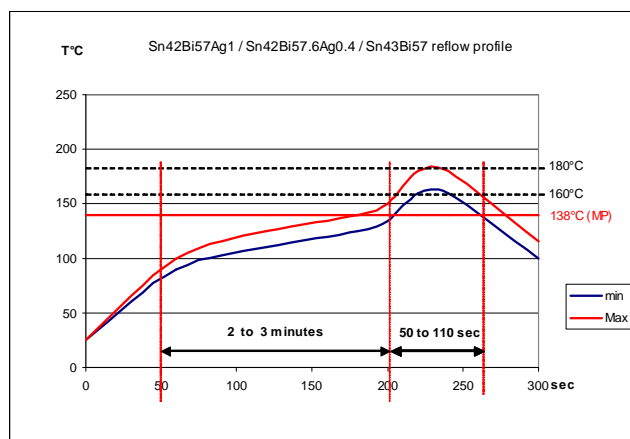
Convection, infrared, vapour phase, hot plate, hot bar, laser and others. Aerobic or inerted.

Heating Profile

See suggested reflow profile for specific alloy.

Cleaning Equipment

Spray, immersion, vapour degreaser or scrubber.



Packaging: jars of 250g, 500g - cartridges of 500 and 1000 g - Proflo[®] of 800g - others on request.

Storage: in original container between 5 and 10°C for up to 12 months. Wait until the pot has reached the ambient temperature before opening to avoid water condensation on the surface of the paste. Once opened, do not return to the fridge. Should be stored at ambient conditions within two weeks.

Additional information:

Our manufacturing processes have been subjected to FMECA analysis (equivalent of AMDEC in Europe).